

## LM317L-N 3-Terminal Adjustable Regulator

Check for Samples: [LM317L-N](#)

### FEATURES

- Adjustable Output Down to 1.2V
- 100mA Output Current
- Line Regulation Typically 0.01%V
- Load Regulation Typically 0.1%
- Current Limit Constant with Temperature
- Eliminates the Need to Stock Many Voltages
- Standard 3-lead Transistor Package
- 80dB Ripple Rejection
- Available in TO-92, SOIC-8, or 6-DSBGA Package
- Output is Short Circuit Protected
- See AN-1112 ([SNVA009](#)) for DSBGA Considerations

### DESCRIPTION

The LM317L-N is an adjustable 3-terminal positive voltage regulator capable of supplying 100mA over a 1.2V to 37V output range. It is exceptionally easy to use and requires only two external resistors to set the output voltage. Further, both line and load regulation are better than standard fixed regulators. Also, the LM317L-N is available packaged in a standard TO-92 transistor package which is easy to use.

In addition to higher performance than fixed regulators, the LM317L-N offers full overload protection. Included on the chip are current limit, thermal overload protection and safe area protection. All overload protection circuitry remains fully functional even if the adjustment terminal is disconnected.

Normally, no capacitors are needed unless the device is situated more than 6 inches from the input filter capacitors in which case an input bypass is needed. An optional output capacitor can be added to improve transient response. The adjustment terminal can be bypassed to achieve very high ripple rejection ratios which are difficult to achieve with standard 3-terminal regulators.

Besides replacing fixed regulators, the LM317L-N is useful in a wide variety of other applications. Since the regulator is “floating” and sees only the input-to-output differential voltage, supplies of several hundred volts can be regulated as long as the maximum input-to-output differential is not exceeded.

Also, it makes an especially simple adjustable switching regulator, a programmable output regulator, or by connecting a fixed resistor between the adjustment and output, the LM317L-N can be used as a precision current regulator. Supplies with electronic shutdown can be achieved by clamping the adjustment terminal to ground which programs the output to 1.2V where most loads draw little current.

The LM317L-N is available in a standard TO-92 transistor package, the SOIC-8 package, and 6-DSBGA package. The LM317L-N is rated for operation over a  $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$  range.

### Connection Diagram

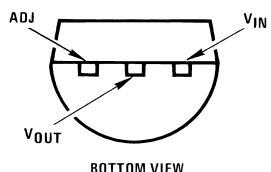


Figure 1. TO-92 Plastic package

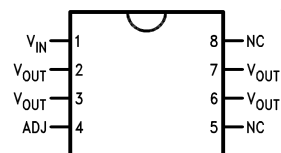
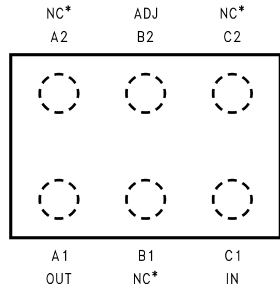


Figure 2. 8-Pin SOIC - Top View



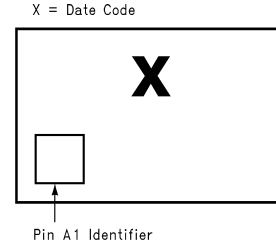
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\*NC = Not Internally connected.

**Figure 3. 6-DSBGA - Top View (Bump Side Down)**



**Figure 4. DSBGA Laser Mark**



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

**Absolute Maximum Rating <sup>(1)(2)</sup>**

Power Dissipation		Internally Limited
Input-Output Voltage Differential		40V
Operating Junction Temperature Range		-40°C to +125°C
Storage Temperature		-55°C to +150°C
Lead Temperature (Soldering, 4 seconds)		260°C
Output is Short Circuit Protected ESD Susceptibility	Human Body Mode <sup>(3)</sup>	2kV

- (1) "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
- (3) The human body model is a 100pF capacitor discharged through a 1.5kΩ resistor into each pin.

**Electrical Characteristics** <sup>(1)</sup>

Parameter	Conditions	Min	Typ	Max	Units
Line Regulation	$T_J = 25^\circ\text{C}$ , $3\text{V} \leq (V_{IN} - V_{OUT}) \leq 40\text{V}$ , $I_L \leq 20\text{mA}$ <sup>(2)</sup>		0.01	0.04	%/V
Load Regulation	$T_J = 25^\circ\text{C}$ , $5\text{mA} \leq I_{OUT} \leq I_{MAX}$ <sup>(2)</sup>		0.1	0.5	%
Thermal Regulation	$T_J = 25^\circ\text{C}$ , 10ms Pulse		0.04	0.2	%/W
Adjustment Pin Current			50	100	$\mu\text{A}$
Adjustment Pin Current	$5\text{mA} \leq I_L \leq 100\text{mA}$		0.2	5	$\mu\text{A}$
Change	$3\text{V} \leq (V_{IN} - V_{OUT}) \leq 40\text{V}$ , $P \leq 625\text{mW}$				
Reference Voltage	$3\text{V} \leq (V_{IN} - V_{OUT}) \leq 40\text{V}$ <sup>(3)</sup> $5\text{mA} \leq I_{OUT} \leq 100\text{mA}$ , $P \leq 625\text{mW}$	1.20	1.25	1.30	V
Line Regulation	$3\text{V} \leq (V_{IN} - V_{OUT}) \leq 40\text{V}$ , $I_L \leq 20\text{mA}$ <sup>(2)</sup>		0.02	0.07	%/V
Load Regulation	$5\text{mA} \leq I_{OUT} \leq 100\text{mA}$ <sup>(2)</sup>		0.3	1.5	%
Temperature Stability	$T_{MIN} \leq T_J \leq T_{MAX}$		0.65		%
Minimum Load Current	$(V_{IN} - V_{OUT}) \leq 40\text{V}$		3.5	5	mA
	$3\text{V} \leq (V_{IN} - V_{OUT}) \leq 15\text{V}$		1.5	2.5	
Current Limit	$3\text{V} \leq (V_{IN} - V_{OUT}) \leq 13\text{V}$	100	200	300	mA
	$(V_{IN} - V_{OUT}) = 40\text{V}$	25	50	150	mA
Rms Output Noise, % of $V_{OUT}$	$T_J = 25^\circ\text{C}$ , $10\text{Hz} \leq f \leq 10\text{kHz}$		0.003		%
Ripple Rejection Ratio	$V_{OUT} = 10\text{V}$ , $f = 120\text{Hz}$ , $C_{ADJ} = 0$		65		dB
	$C_{ADJ} = 10\mu\text{F}$	66	80		dB
Long-Term Stability	$T_J = 125^\circ\text{C}$ , 1000 Hours		0.3	1	%
Junction to Ambient Thermal Resistance	Z Package 0.4" Leads		180		$^\circ\text{C}/\text{W}$
	Z Package 0.125 Leads		160		$^\circ\text{C}/\text{W}$
	SOIC-8 Package		165		$^\circ\text{C}/\text{W}$
	6-DSBGA		290		$^\circ\text{C}/\text{W}$

- (1) Unless otherwise noted, these specifications apply:  $-25^\circ\text{C} \leq T_J \leq 125^\circ\text{C}$  for the LM317L-N;  $V_{IN} - V_{OUT} = 5\text{V}$  and  $I_{OUT} = 40\text{mA}$ . Although power dissipation is internally limited, these specifications are applicable for power dissipations up to 625mW.  $I_{MAX}$  is 100mA.
- (2) Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output voltage due to heating effects are covered under the specification for thermal regulation.
- (3) Thermal resistance of the TO-92 package is  $180^\circ\text{C}/\text{W}$  junction to ambient with 0.4" leads from a PC board and  $160^\circ\text{C}/\text{W}$  junction to ambient with 0.125" lead length to PC board.

### Typical Performance Characteristics

(Output capacitor = 0 $\mu$ F unless otherwise noted.)

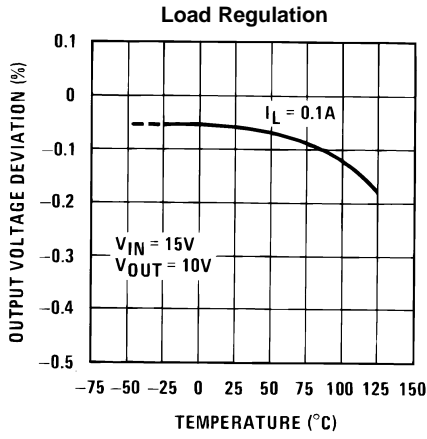


Figure 5.

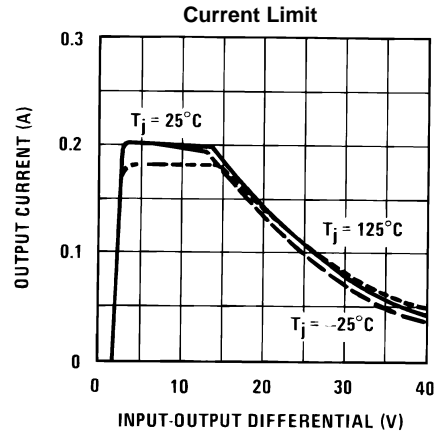


Figure 6.

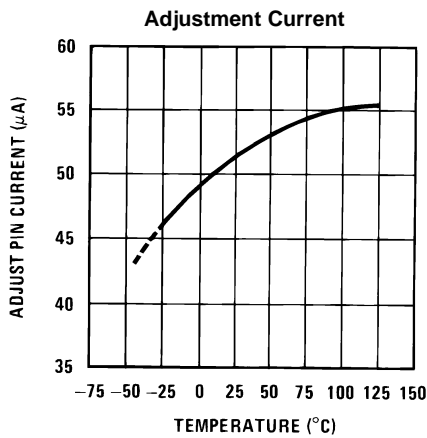


Figure 7.

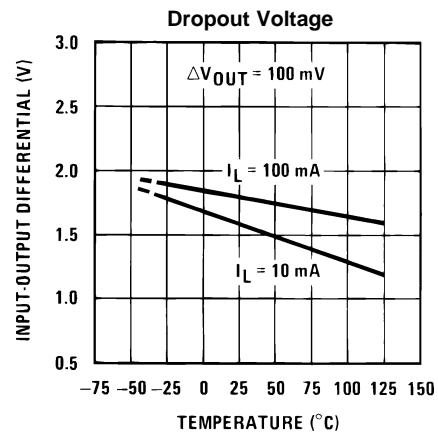


Figure 8.

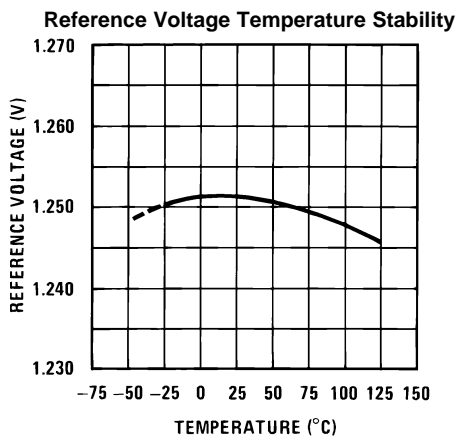


Figure 9.

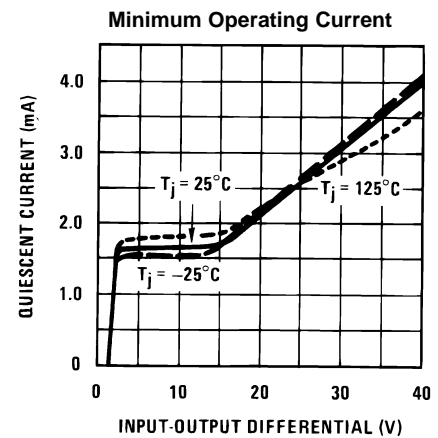
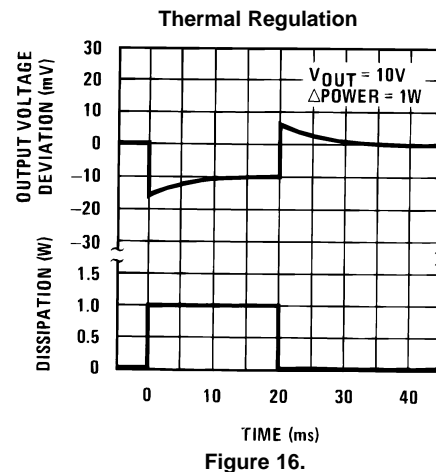
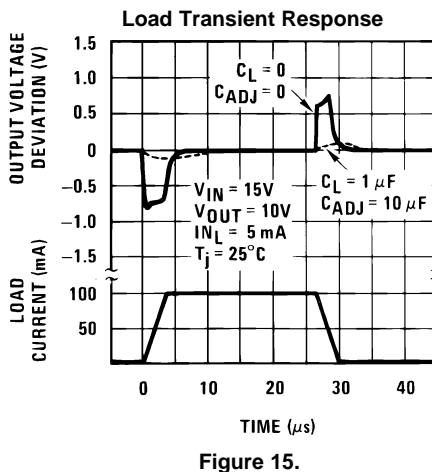
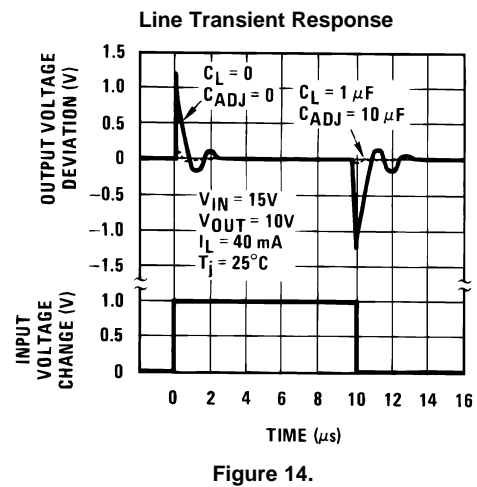
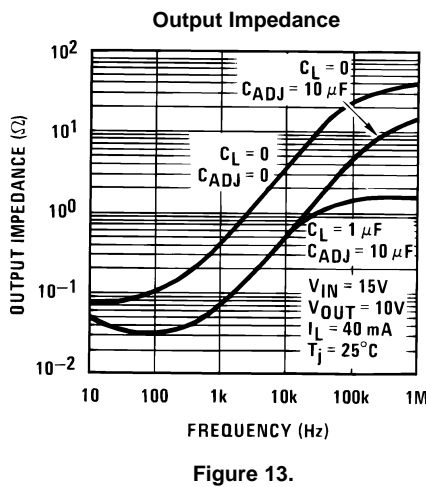
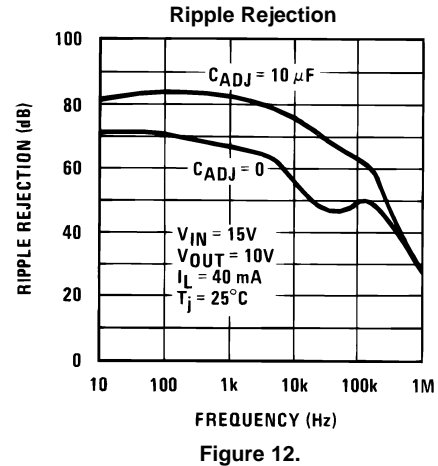
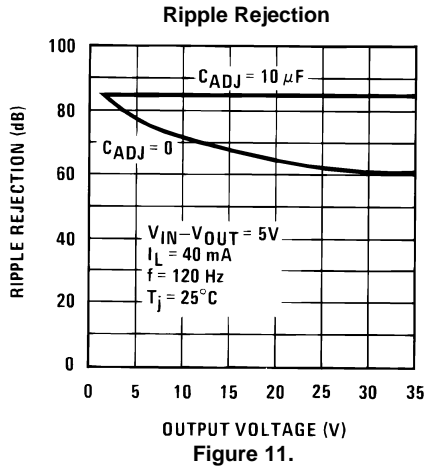


Figure 10.

Typical Performance Characteristics (continued)

(Output capacitor = 0μF unless otherwise noted.)

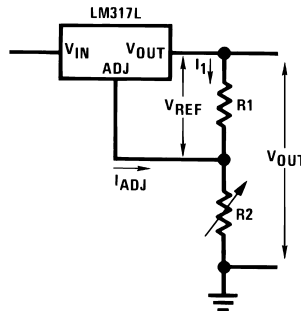


## APPLICATION HINTS

In operation, the LM317L-N develops a nominal 1.25V reference voltage,  $V_{REF}$ , between the output and adjustment terminal. The reference voltage is impressed across program resistor  $R1$  and, since the voltage is constant, a constant current  $I_1$  then flows through the output set resistor  $R2$ , giving an output voltage of

$$V_{OUT} = V_{REF} \left( 1 + \frac{R2}{R1} \right) + I_{ADJ}(R2) \quad (1)$$

Since the 100 $\mu$ A current from the adjustment terminal represents an error term, the LM317L-N was designed to minimize  $I_{ADJ}$  and make it very constant with line and load changes. To do this, all quiescent operating current is returned to the output establishing a minimum load current requirement. If there is insufficient load on the output, the output will rise.



## EXTERNAL CAPACITORS

An input bypass capacitor is recommended in case the regulator is more than 6 inches away from the usual large filter capacitor. A 0.1 $\mu$ F disc or 1 $\mu$ F solid tantalum on the input is suitable input bypassing for almost all applications. The device is more sensitive to the absence of input bypassing when adjustment or output capacitors are used, but the above values will eliminate the possibility of problems.

The adjustment terminal can be bypassed to ground on the LM317L-N to improve ripple rejection and noise. This bypass capacitor prevents ripple and noise from being amplified as the output voltage is increased. With a 10 $\mu$ F bypass capacitor 80dB ripple rejection is obtainable at any output level. Increases over 10 $\mu$ F do not appreciably improve the ripple rejection at frequencies above 120Hz. If the bypass capacitor is used, it is sometimes necessary to include protection diodes to prevent the capacitor from discharging through internal low current paths and damaging the device.

In general, the best type of capacitors to use is solid tantalum. *Solid tantalum capacitors have low impedance even at high frequencies.* Depending upon capacitor construction, it takes about 25 $\mu$ F in aluminum electrolytic to equal 1 $\mu$ F solid tantalum at high frequencies. Ceramic capacitors are also good at high frequencies; but some types have a large decrease in capacitance at frequencies around 0.5MHz. For this reason, a 0.01 $\mu$ F disc may seem to work better than a 0.1 $\mu$ F disc as a bypass.

Although the LM317L-N is stable with no output capacitors, like any feedback circuit, certain values of external capacitance can cause excessive ringing. This occurs with values between 500pF and 5000pF. A 1 $\mu$ F solid tantalum (or 25 $\mu$ F aluminum electrolytic) on the output swamps this effect and insures stability.

## LOAD REGULATION

The LM317L-N is capable of providing extremely good load regulation but a few precautions are needed to obtain maximum performance. The current set resistor connected between the adjustment terminal and the output terminal (usually 240 $\Omega$ ) should be tied directly to the output of the regulator rather than near the load. This eliminates line drops from appearing effectively in series with the reference and degrading regulation. For example, a 15V regulator with 0.05 $\Omega$  resistance between the regulator and load will have a load regulation due to line resistance of  $0.05\Omega \times I_L$ . If the set resistor is connected near the load the effective line resistance will be  $0.05\Omega (1 + R2/R1)$  or in this case, 11.5 times worse.

Figure 17 shows the effect of resistance between the regulator and 240 $\Omega$  set resistor.

With the TO-92 package, it is easy to minimize the resistance from the case to the set resistor, by using two separate leads to the output pin. The ground of  $R2$  can be returned near the ground of the load to provide remote ground sensing and improve load regulation.

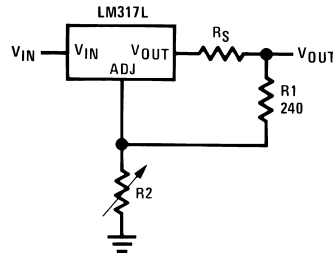


Figure 17. Regulator with Line Resistance in Output Lead

## THERMAL REGULATION

When power is dissipated in an IC, a temperature gradient occurs across the IC chip affecting the individual IC circuit components. With an IC regulator, this gradient can be especially severe since power dissipation is large. Thermal regulation is the effect of these temperature gradients on output voltage (in percentage output change) per watt of power change in a specified time. Thermal regulation error is independent of electrical regulation or temperature coefficient, and occurs within 5ms to 50ms after a change in power dissipation. Thermal regulation depends on IC layout as well as electrical design. The thermal regulation of a voltage regulator is defined as the percentage change of  $V_{OUT}$ , per watt, within the first 10ms after a step of power is applied. The LM317L-N specification is 0.2%/W, maximum.

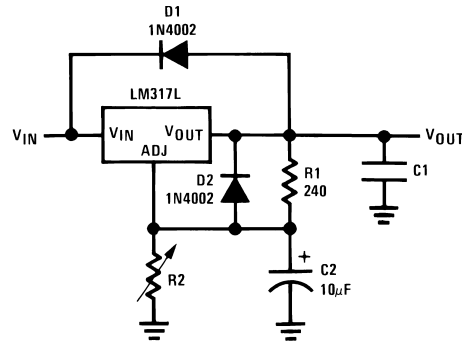
In the Thermal Regulation curve at the bottom of the Typical Performance Characteristics page, a typical LM317L-N's output changes only 7mV (or 0.07% of  $V_{OUT} = -10V$ ) when a 1W pulse is applied for 10ms. This performance is thus well inside the specification limit of  $0.2\%/W \times 1W = 0.2\%$  maximum. When the 1W pulse is ended, the thermal regulation again shows a 7mV change as the gradients across the LM317L-N chip die out. Note that the load regulation error of about 14mV (0.14%) is additional to the thermal regulation error.

## PROTECTION DIODES

When external capacitors are used with *any* IC regulator it is sometimes necessary to add protection diodes to prevent the capacitors from discharging through low current points into the regulator. Most 10 $\mu$ F capacitors have low enough internal series resistance to deliver 20A spikes when shorted. Although the surge is short, there is enough energy to damage parts of the IC.

When an output capacitor is connected to a regulator and the input is shorted, the output capacitor will discharge into the output of the regulator. The discharge current depends on the value of the capacitor, the output voltage of the regulator, and the rate of decrease of  $V_{IN}$ . In the LM317L-N, this discharge path is through a large junction that is able to sustain a 2A surge with no problem. This is not true of other types of positive regulators. For output capacitors of 25  $\mu$ F or less, the LM317L-N's ballast resistors and output structure limit the peak current to a low enough level so that there is no need to use a protection diode.

The bypass capacitor on the adjustment terminal can discharge through a low current junction. Discharge occurs when *either* the input or output is shorted. Internal to the LM317L-N is a 50 $\Omega$  resistor which limits the peak discharge current. No protection is needed for output voltages of 25V or less and 10 $\mu$ F capacitance. [Figure 18](#) shows an LM317L-N with protection diodes included for use with outputs greater than 25V and high values of output capacitance.



$$V_{OUT} = V_{REF} \left( 1 + \frac{R2}{R1} \right) + I_{ADJ}(R2)$$

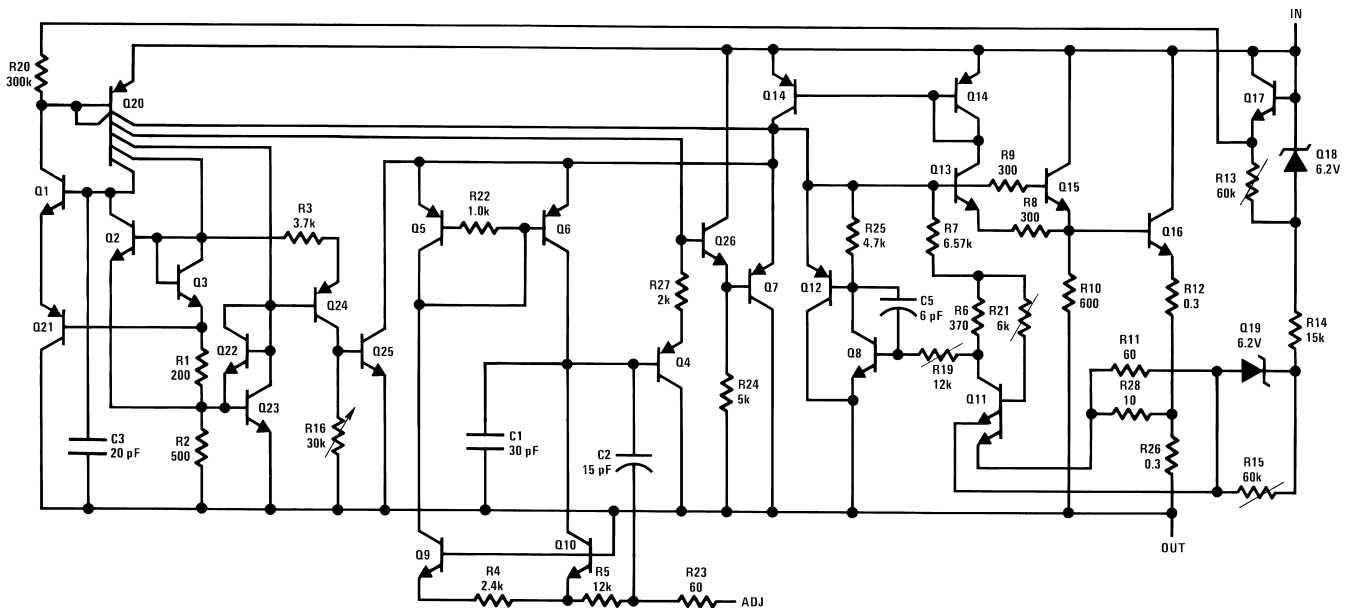
D1 protects against C1  
 D2 protects against C2

Figure 18. Regulator with Protection Diodes

**LM317L-N DSBGA Light Sensitivity**

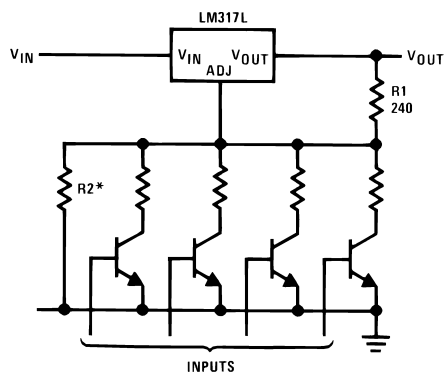
Exposing the LM317L-N DSBGA package to bright sunlight may cause the  $V_{REF}$  to drop. In a normal office environment of fluorescent lighting the output is not affected. The LM317 DSBGA does not sustain permanent damage from light exposure. Removing the light source will cause LM317L-N's  $V_{REF}$  to recover to the proper value.

**Schematic Diagram**





Typical Applications



\*Sets maximum  $V_{OUT}$

Figure 19. Digitally Selected Outputs

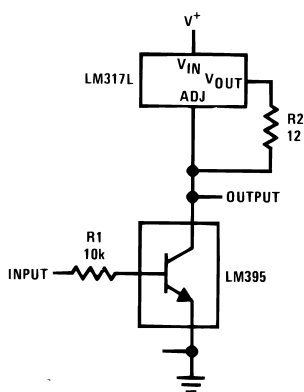
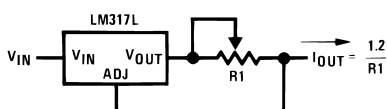


Figure 20. High Gain Amplifier



$12 \leq R1 \leq 240$

Figure 21. Adjustable Current Limiter

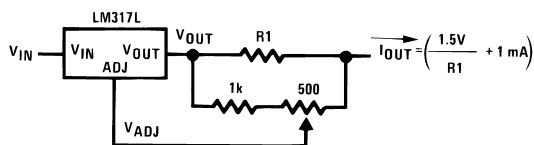


Figure 22. Precision Current Limiter

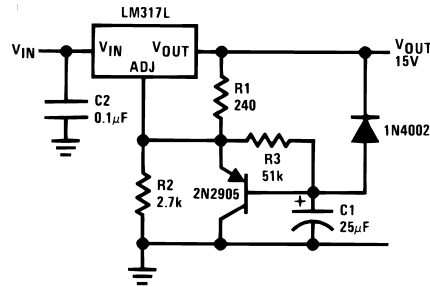
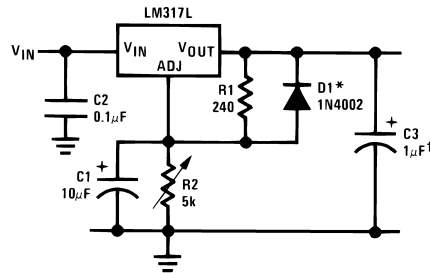


Figure 23. Slow Turn-On 15V Regulator



†Solid tantalum

\*Discharges C1 if output is shorted to ground

Figure 24. Adjustable Regulator with Improved Ripple Rejection

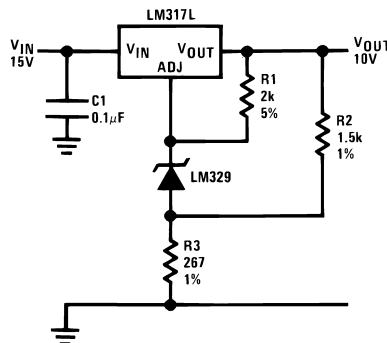
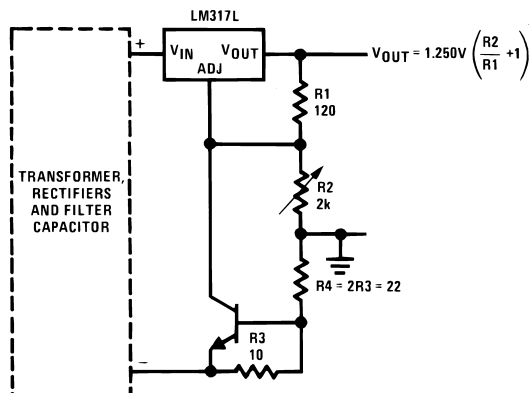
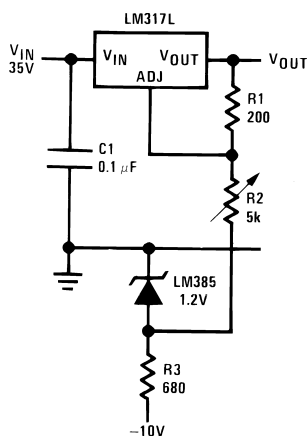


Figure 25. High Stability 10V Regulator



Short circuit current is approximately  $600 \text{ mV}/R_3$ , or 60mA (compared to LM317L-NZ's 200mA current limit). At 25mA output only 3/4V of drop occurs in R3 and R4.

Figure 26. Adjustable Regulator with Current Limiter



Full output current not available at high input-output voltages

Figure 27. 0V–30V Regulator

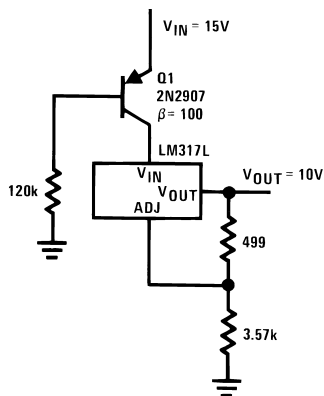


Figure 28. Regulator With 15mA Short Circuit Current

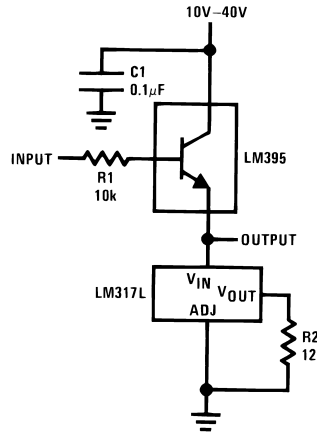
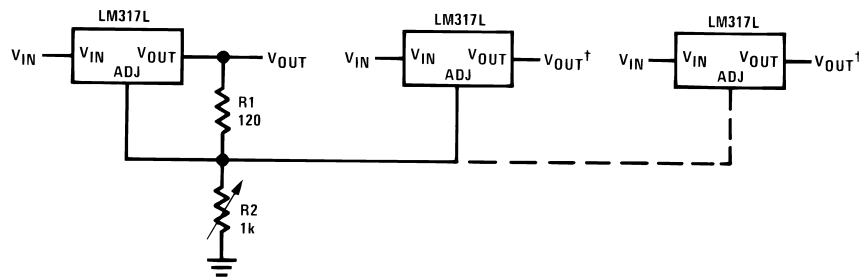


Figure 29. Power Follower



\*All outputs within  $\pm 100\text{mV}$   
 †Minimum load  $-5\text{mA}$

Figure 30. Adjusting Multiple On-Card Regulators with Single Control\*

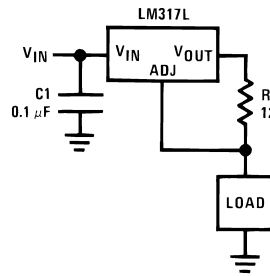
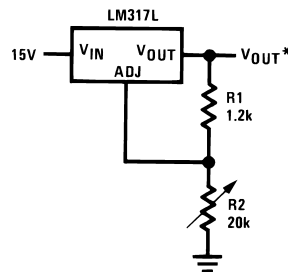


Figure 31. 100mA Current Regulator



\*Minimum load current  $\approx 2\text{mA}$

Figure 32. 1.2V–12V Regulator with Minimum Program Current

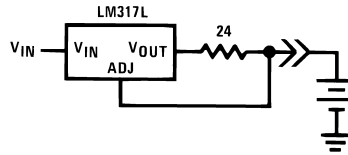
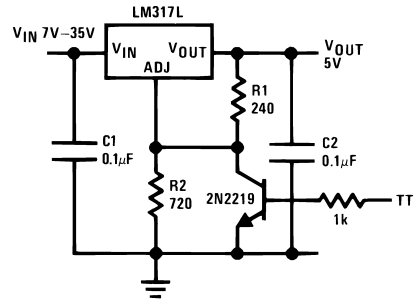
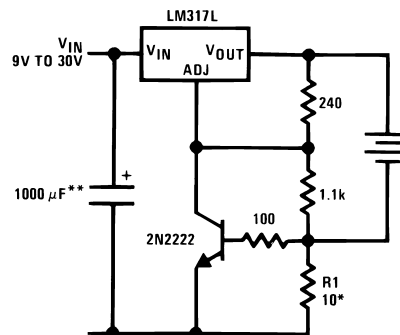


Figure 33. 50mA Constant Current Battery Charger for Nickel-Cadmium Batteries



\*Minimum output  $\approx 1.2V$

Figure 34. 5V Logic Regulator with Electronic Shutdown\*



\*Sets peak current,  $I_{PEAK} = 0.6V/R1$

\*\*1000µF is recommended to filter out any input transients.

Figure 35. Current Limited 6V Charger

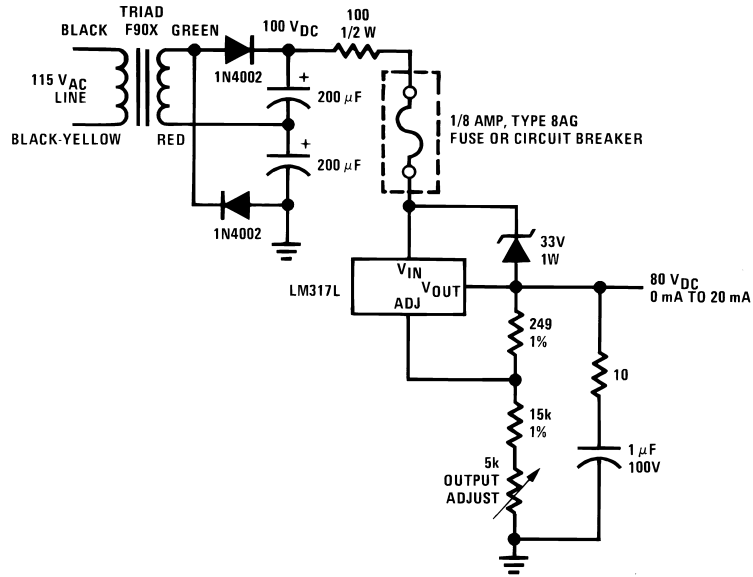
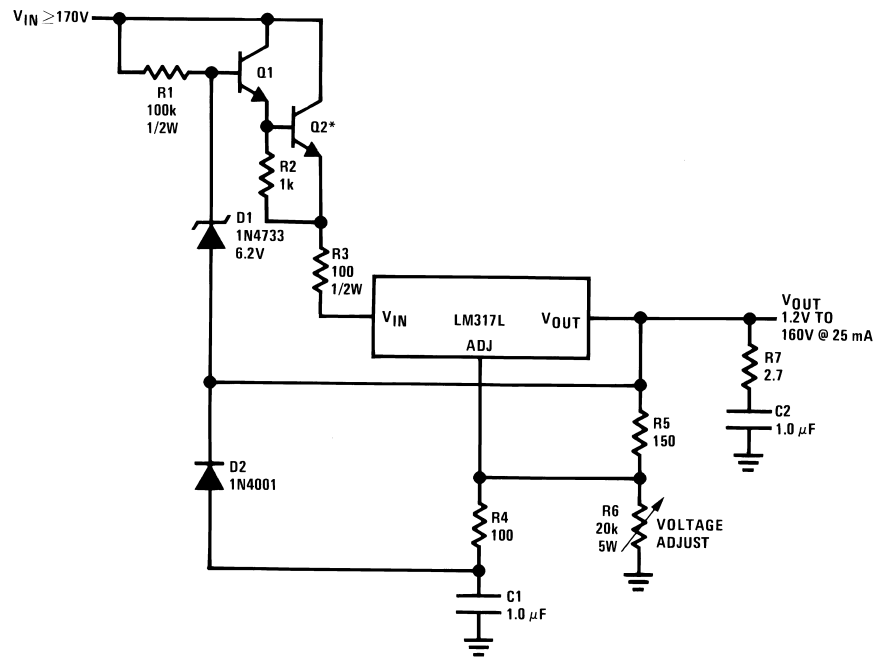
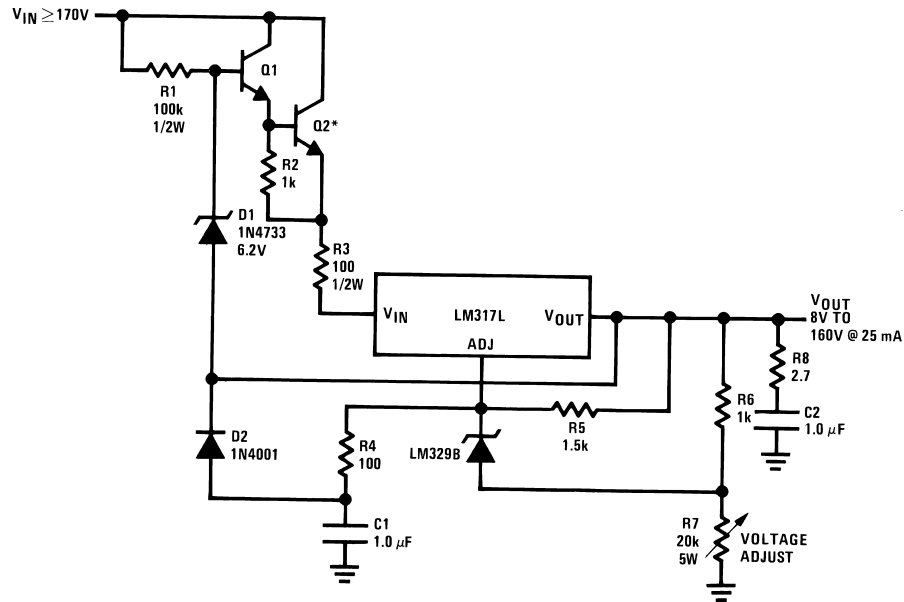


Figure 36. Short Circuit Protected 80V Supply



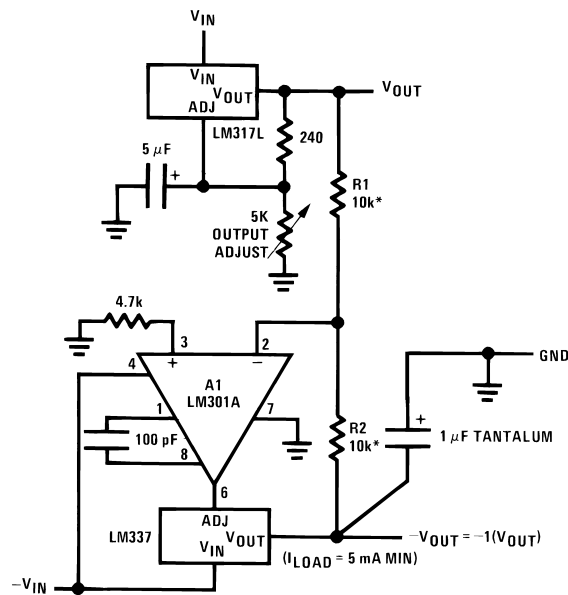
Q1, Q2: NSD134 or similar  
 C1, C2: 1µF, 200V mylar\*\*  
 \*Heat sink

Figure 37. Basic High Voltage Regulator



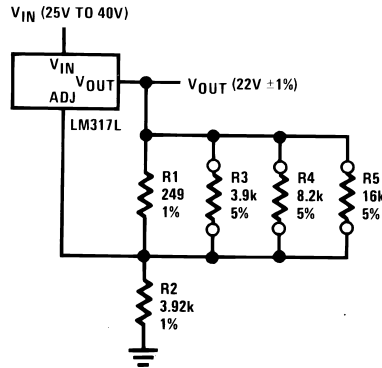
Q1, Q2: NSD134 or similar  
 C1, C2: 1 μF, 200V mylar\*\*  
 \*Heat sink  
 \*\*Mylar is a registered trademark of DuPont Co.

Figure 38. Precision High Voltage Regulator



A1 = LM301A, LM307, or LF13741 only  
 R1, R2 = matched resistors with good TC tracking

Figure 39. Tracking Regulator

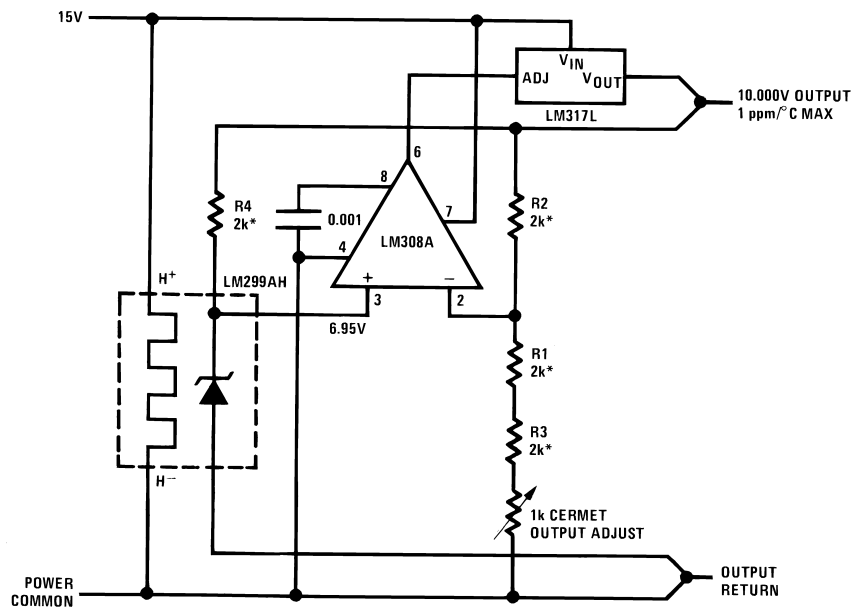


**Trim Procedure:**

- If  $V_{OUT}$  is 23.08V or higher, cut out R3 (if lower, don't cut it out).
- Then if  $V_{OUT}$  is 22.47V or higher, cut out R4 (if lower, don't).
- Then if  $V_{OUT}$  is 22.16V or higher, cut out R5 (if lower, don't).

This will trim the output to well within  $\pm 1\%$  of 22.00  $V_{DC}$ , without any of the expense or uncertainty of a trim pot (see LB-46). Of course, this technique can be used at any output voltage level.

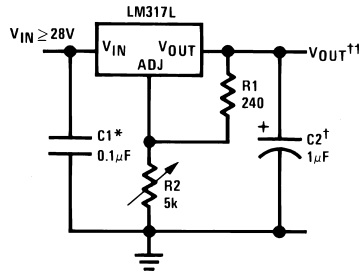
**Figure 40. Regulator With Trimmable Output Voltage**



\*R1–R4 from thin-film network, Beckman 694-3-R2K-D or similar

**Figure 41. Precision Reference with Short-Circuit Proof Output**





Full output current not available at high input-output voltages

†Optional—improves transient response

\*Needed if device is more than 6 inches from filter capacitors

$$\dagger\dagger V_{OUT} = 1.25V \left( 1 + \frac{R_2}{R_1} \right) + I_{ADJ}(R_2)$$

Figure 42. 1.2V-25 Adjustable Regulator

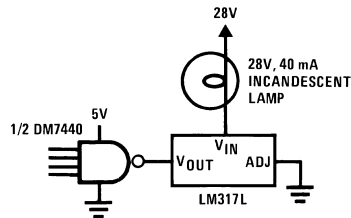
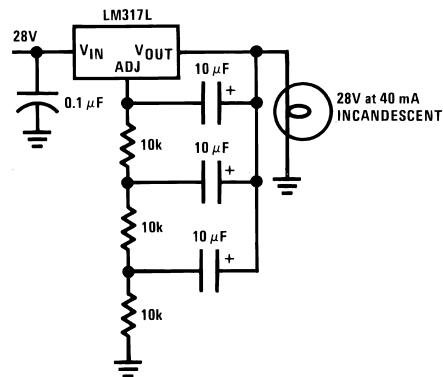


Figure 43. Fully Protected (Bulletproof) Lamp Driver



Output rate—4 flashes per second at 10% duty cycle

Figure 44. Lamp Flasher

## REVISION HISTORY

Changes from Revision I (March 2013) to Revision J	Page
• Changed layout of National Data Sheet to TI format .....	<a href="#">9</a>

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM317LITP/NOPB	ACTIVE	DSBGA	YPB	6	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	P 1	<a href="#">Samples</a>
LM317LITPX/NOPB	ACTIVE	DSBGA	YPB	6	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	P 1	<a href="#">Samples</a>
LM317LM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	LM317 LM	<a href="#">Samples</a>
LM317LMX	NRND	SOIC	D	8	2500	TBD	Call TI	Call TI	-40 to 125	LM317 LM	
LM317LMX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	SN   CU SN	Level-1-260C-UNLIM	-40 to 125	LM317 LM	<a href="#">Samples</a>
LM317LZ/LFT1	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SN   CU SN	N / A for Pkg Type		LM317 LZ	<a href="#">Samples</a>
LM317LZ/LFT2	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SN   CU SN	N / A for Pkg Type		LM317 LZ	<a href="#">Samples</a>
LM317LZ/LFT3	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SN   CU SN	N / A for Pkg Type		LM317 LZ	<a href="#">Samples</a>
LM317LZ/LFT4	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SN   CU SN	N / A for Pkg Type		LM317 LZ	<a href="#">Samples</a>
LM317LZ/LFT7	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SN   CU SN	N / A for Pkg Type		LM317 LZ	<a href="#">Samples</a>
LM317LZ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	SNCU   CU SN	N / A for Pkg Type	-40 to 125	LM317 LZ	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

---

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM317LITP/NOPB	DSBGA	YPB	6	250	178.0	8.4	1.09	1.75	0.66	4.0	8.0	Q1
LM317LITPX/NOPB	DSBGA	YPB	6	3000	178.0	8.4	1.09	1.75	0.66	4.0	8.0	Q1
LM317LMX	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM317LMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM317LITP/NOPB	DSBGA	YPB	6	250	210.0	185.0	35.0
LM317LITPX/NOPB	DSBGA	YPB	6	3000	210.0	185.0	35.0
LM317LMX	SOIC	D	8	2500	367.0	367.0	35.0
LM317LMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE

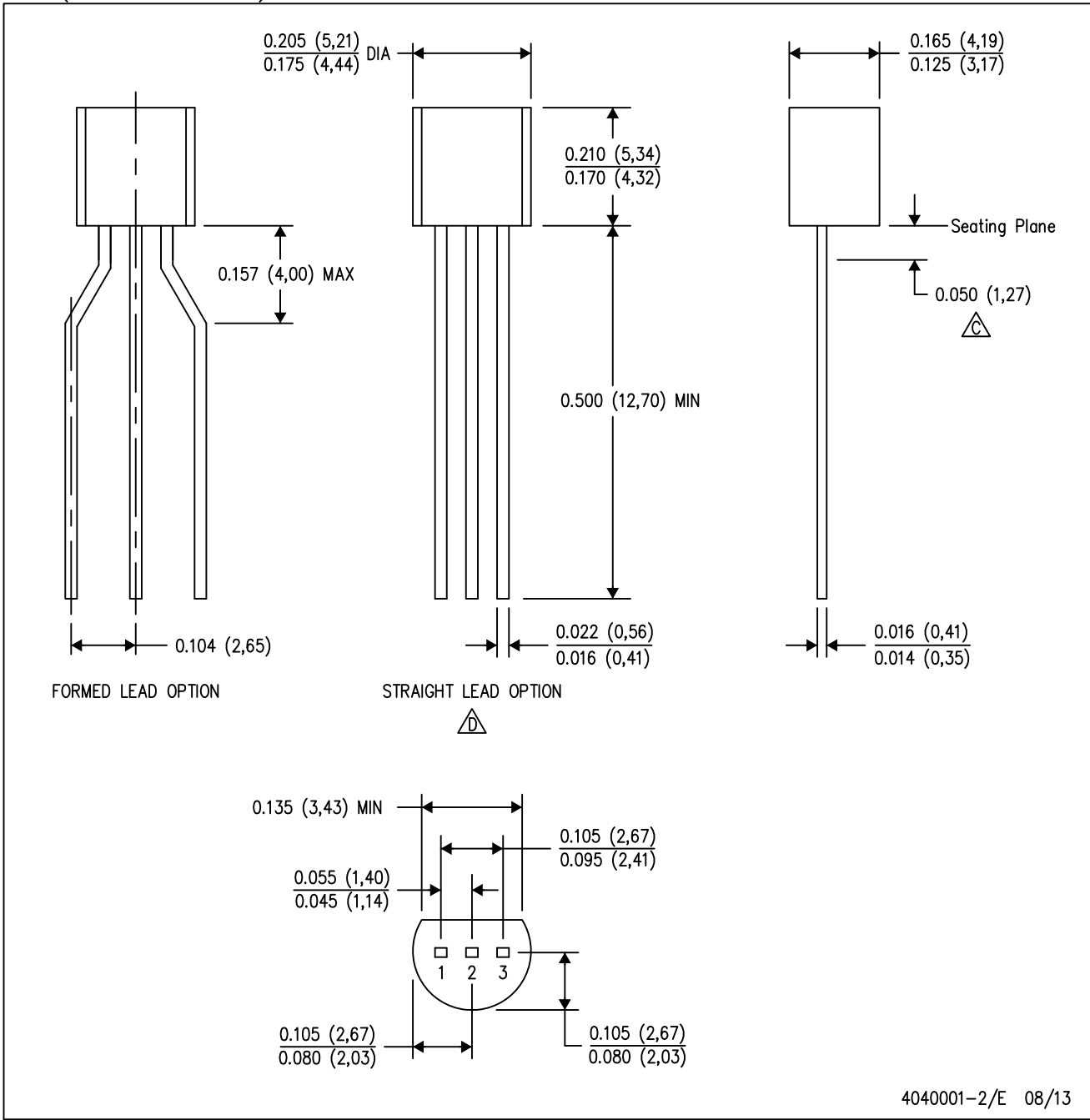


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AA.



**MECHANICAL DATA**

LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



4040001-2/E 08/13

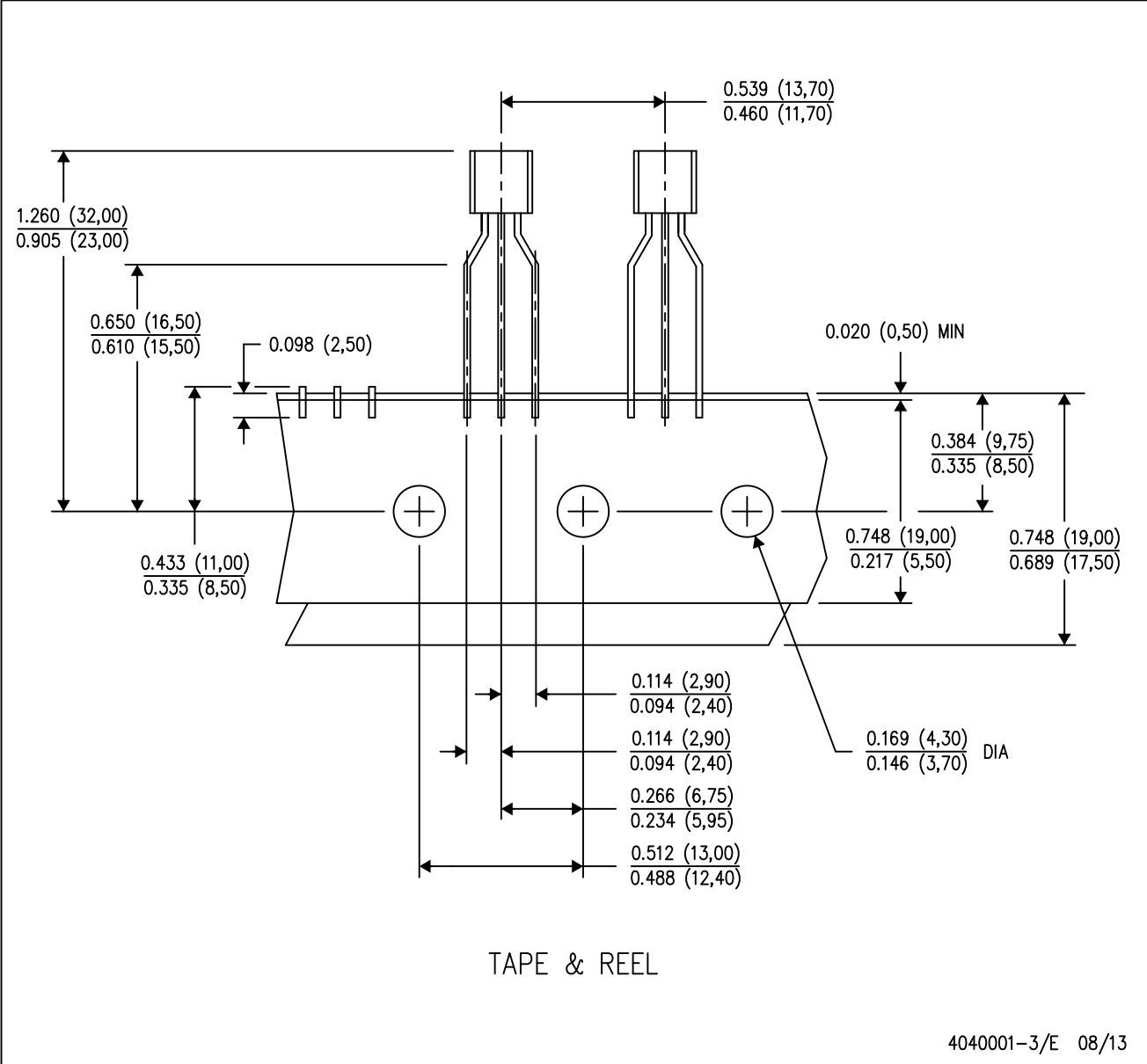
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  Lead dimensions are not controlled within this area.
  -  Falls within JEDEC TO-226 Variation AA (TO-226 replaces TO-92).
  - E. Shipping Method:  
 Straight lead option available in bulk pack only.  
 Formed lead option available in tape & reel or ammo pack.  
 Specific products can be offered in limited combinations of shipping mediums and lead options.  
 Consult product folder for more information on available options.



**MECHANICAL DATA**

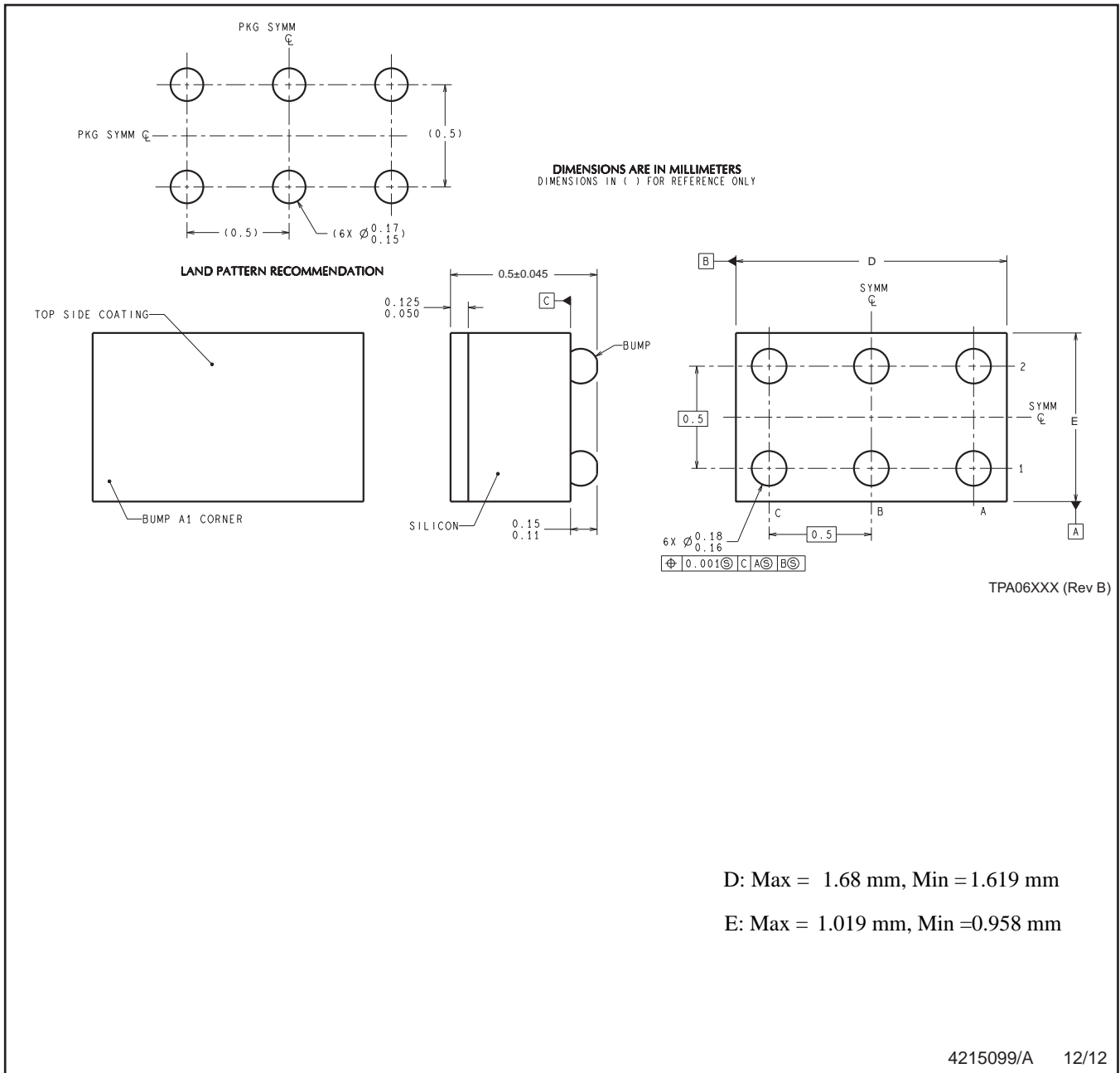
LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Tape and Reel information for the Formed Lead Option package.

YPB0006



D: Max = 1.68 mm, Min = 1.619 mm

E: Max = 1.019 mm, Min = 0.958 mm

4215099/A 12/12

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.  
B. This drawing is subject to change without notice.

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